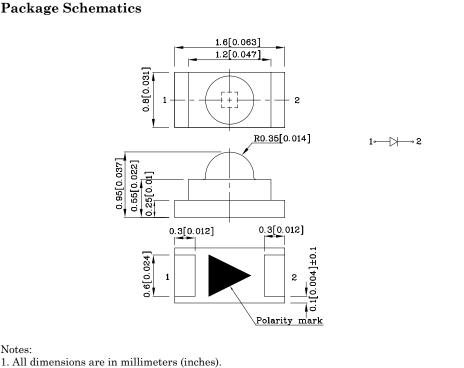


Part Number: XZMDK53W-8

1.6X0.8mm SMD CHIP LED LAMP

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- \bullet RoHS compliant





2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Red (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA	
Power Dissipation	PD	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	-0	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Red (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.95	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	uA	
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	645*	nm	
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	630*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	28	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	35	$_{\rm pF}$	

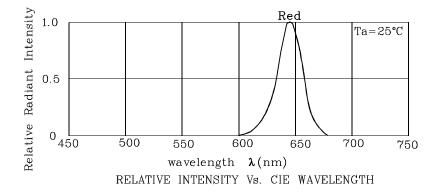
Part Number	Emitting Color	Emitting Material	Lens-color	CIE12' (I _F =2	s Intensity 7-2007* 0mA) cd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMDK53W-8	Red	AlGaInP	Water Clear	400 80*	795 248*	645*	60°

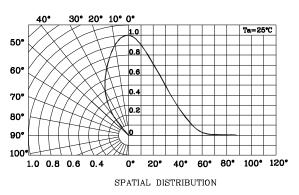
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 22, 2016

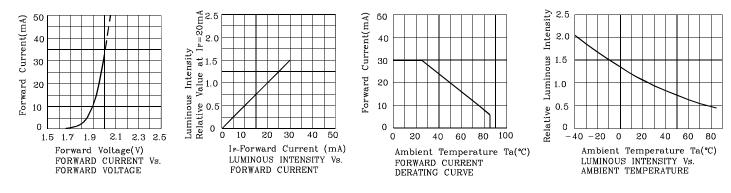
XDSB3738 V4-X Layout: Maggie L.







Red



LED is recommended for reflow soldering and soldering profile is shown below.

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes:

Reflow Soldering Profile for SMD Products (Pb-Free Components)

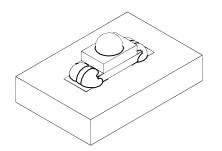
1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

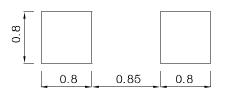
high temperatures conditions



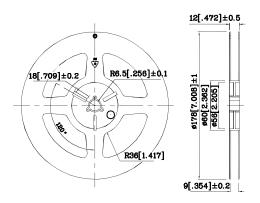
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



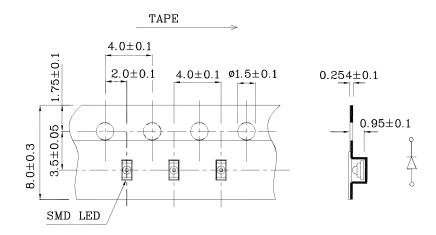
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

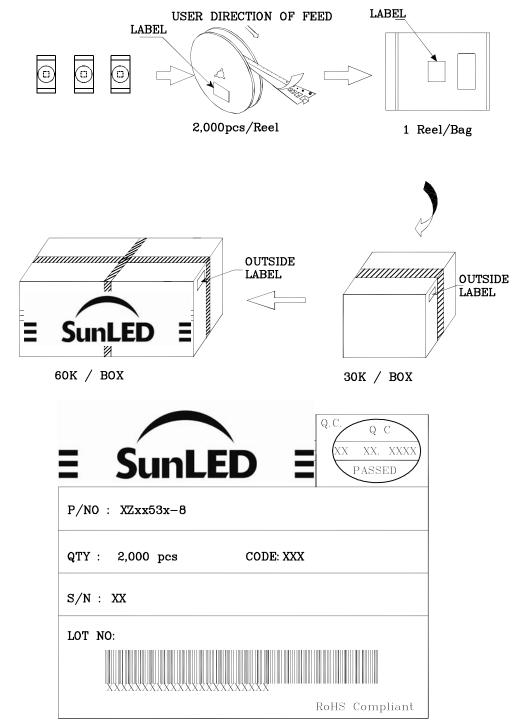
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at <u>http://www.SunLEDusa.com/TechnicalNotes.asp</u>